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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Chen, et al.

Serial No.: 10/741,824

Confirmation No.: 2621

Filed: December 19, 2003

For: Enhancement of Cu Line
Reliability Using Thin ALD
TaN Film to Cap the Cu
Line

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Group Art Unit: 2833

Examiner: Unknown

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

CERTIFICATE OF MAILING 37 CFR 1.8	
I hereby certify that this correspondence is being deposited on <u>11/29</u> , 2005 with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.	
<u>11/29/05</u> Date	<u>[Signature]</u> Signature

STATUS INQUIRY

More than 23 months have passed since

☒ the filing of this application on December 19, 2003.

No communication has been received from the Patent and Trademark Office
indicating action on this application or response.

Kindly advise the undersigned of the present status of this application. A
stamped return-addressed envelope is provided.

Respectfully submitted,

[Signature]
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